

SPECIFICATION SHEET

SPECIFICATION SHEET NO.	N0626-UMSB30M000S30A
DATE	June 26, 2021
REVISION	A0
DESCRIPTION	SMD Single Phase Glass Passivated Bridge Rectifier, UMSB Series, MSB30M Type 4 Pins, Reverse Voltage 1000V Max. Forward Current 3.0A Max. Operating Temp. Range -55°C ~+150°C, Package in Tape/Reel, 3000pcs/R RoHS/RoHS III compliant
CUSTOMER	
CUSTOMER PART NUMBER	
CROSS REF. PART NUMBER	
ORIGINAL PART NUMBER	MDD MSB30M
PART CODE	UMSB30M000S30A

VENDOR APPROVE		
Issued/Checked/Approved	  	
DATE: June 26, 2021		

CUSTOMER APPROVE
DATE:

SMD BRIDGE RECTIFIER UMSB SERIES

MAIN FEATURE

- Glass passivated chip junction
- Reverse voltage 1000V
- forward current 3A
- High surge current capability



APPLICATION

- For SMD application

PART CODE GUIDE

RFQ

[Request For Quotation](#)

UMSB	30M000	S	30A
1	2	3	4

- 1) **UMSB**: SMD Single Phase Glass Passivated Bridge Rectifier, 4 pins, UMSB Series
- 2) **30M000**: Type code for original part number MSB30M
- 3) **S**: Package code, Tape/reel, 3000pcs/reel.
- 4) **30A**: Specification code for Reverse Voltage 1000V Max. Forward Current 3.0A Max.

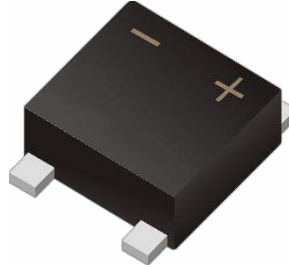
MORE ITEMS AVAILABLE

UMSB30D000S320	UMSB30G000S340	UMSB30J000S360	UMSB30K000S380	UMSB30M000S30A

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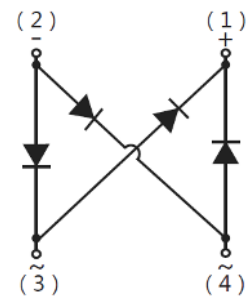
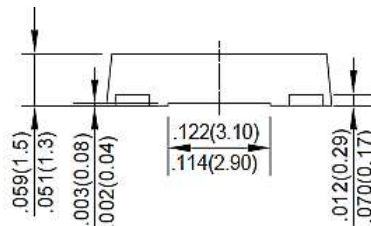
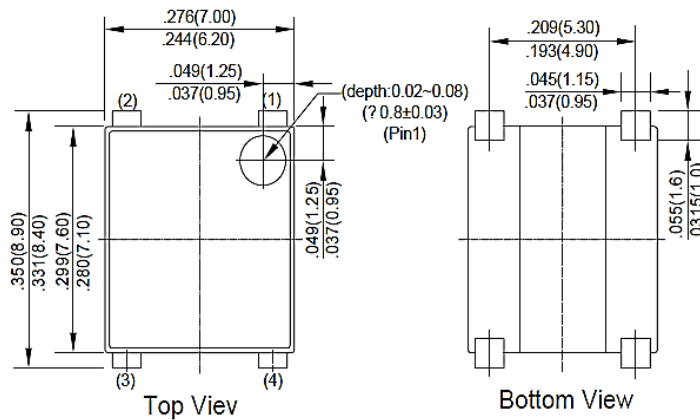
DIMENSION (Unit: Inch/mm)

Image for reference

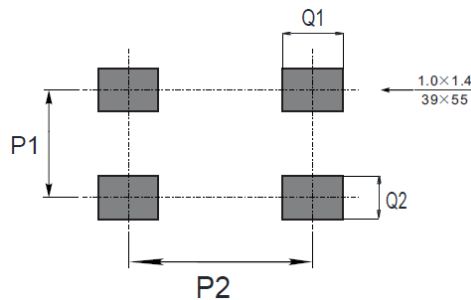


Marking: MSB30M

UMSB



Recommend Pad Layout



Symbol	Min. (Inch)	Min. (mm)
P1	0.201	5.1
P2	0.278	7.1
Q1	0.071	1.8
Q2	0.051	1.3

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MECHANICAL DATA

Case	Terminals	Polarity	Mounting Position	Weight per piece
JEDEC UMSB molded plastic body	Solder plated, Solderable per MIL-STD-750, Method 2026	Polarity symbol marking on case	Any	0.00825 Ounce, 0.234 grams

MAX. RATING & CHARACTERISTICS

Parameter	SYMBOLS	VALUE			UNITS
		Min.	Typical	Max.	
Repetitive peak reverse voltage	V _{RRM}			1000	Volts
RMS voltage	V _{RMS}			700	Volts
DC blocking voltage	V _{DC}			1000	Volts
Average forward output rectified current at T_c= 30°C On glass-epoxy PCB On aluminum substrate	I _{AV}			3.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}		80		A
Instantaneous forward voltage at 3.0A	V _F			1.1	Volts
DC reverse current at rated DC blocking voltage	I _R			5	μA
				100	μA
Junction capacitance (Note 2)	C _J		40		pF
Thermal resistance	R _{QJA}		-		°C/W
Operating junction temperature range	T _J	-55		+150	
Storage temperature range	T _{STG}	-55		+150	°C

Note

1. Ratings at 25 C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.
2. Measured at 1.0MHz and applied reverse voltage of 4Vdc
3. PCB mounted with 4"*1.5"*1.5" copper pad area.

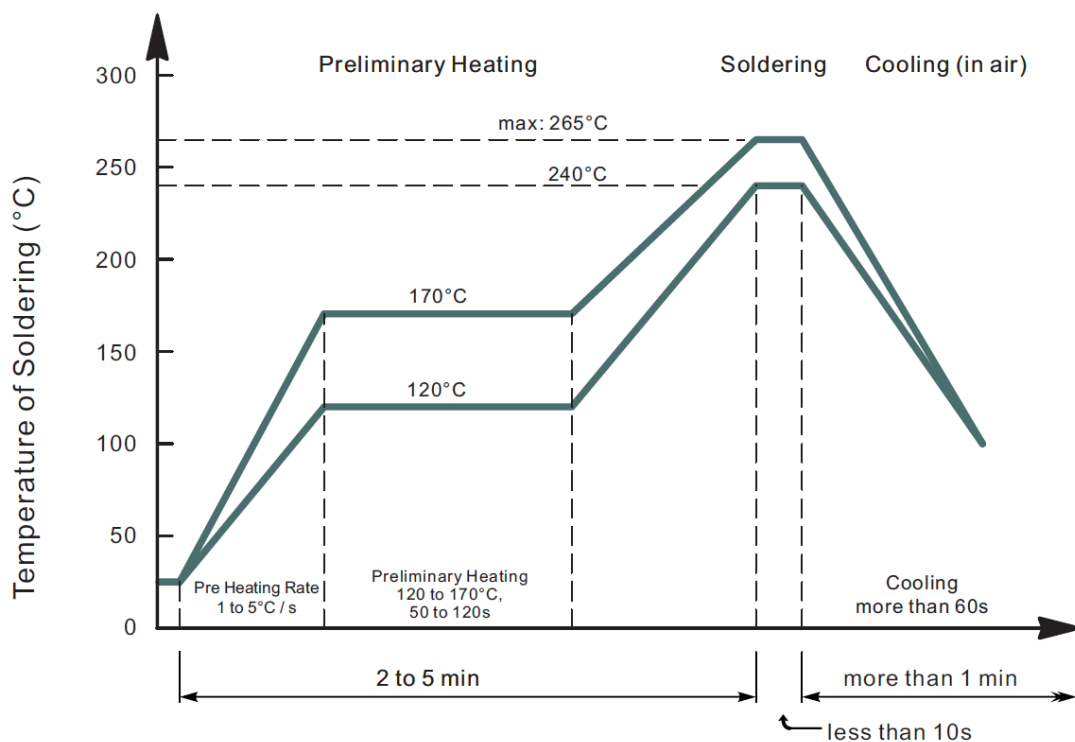
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RELIABILITY

Number	Experiment Items	Experiment Method And Conditions	Reference Documents
1	Solder Resistance Test	Test 260°C± 5°C for 10 ± 2 sec. Immerse body into solder 1/16" ± 1/32"	MIL-STD-750D METHOD-2031.2
2	Solderability Test	230°C ±5°C for 5 sec.	MIL-STD-750D METHOD-2026.1 0
3	Pull Test	1 kg in axial lead direction for 10 sec.	MIL-STD-750D METHOD-2036.4
4	Bend Test	0.5Kg Weight Applied To Each Lead, Bending Arcs 90 °C ± 5 °C For 3 Times	MIL-STD-750D METHOD-2036.4
5	High Temperature Reverse Bias Test	TA=100°C for 1000 Hours at VR=80% Rated VR	MIL-STD-750D METHOD-1038.4
6	Forward Operation Life Test	TA=25°C Rated Average Rectified Current	MIL-STD-750D METHOD-1027.3
7	Intermittent Operation Life Test	On state: 5 min with rated IRMS Power Off state: 5 min with Cool Forced Air. On and off for 1000 cycles.	MIL-STD-750D METHOD-1036.3
8	Pressure Cooker Test	15 PSIG, TA=121°C, 4 hours	MIL-S-19500 APPENIOXC
9	Temperature Cycling Test	-55°C~+125°C; 30 Minutes For Dwelled Time 5 minutes for transferred time. Total: 10 cycles.	MIL-STD-750D METHOD-1051.7
10	Thermal Shock Test	0°C for 5 minutes., 100°C for 5minutes, Total: 10 cycles	MIL-STD-750D METHOD-1056.7
11	Forward Surge Test	8.3ms Single Sale Sine-wave One Surge.	MIL-STD-750D METHOD-4066.4
12	Humidity Test	TA=65°C, RH=98% for 1000 hours.	MIL-STD-750D METHOD-1021.3
13	High Temperature Storage life Test	150°C for 1000 Hours	MIL-STD-750D METHOD-1031.5

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SUGGESTED REFLOW PROFILE (For Reference Only)



- Recommended peak temperature is over 245°C, If peak temperature is below 245 °C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)
- Welding shall not exceed 2 times
- Remark: lead free solder paste (96.5 sn/3.0 Ag/0.5Cu)

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RATINGS AND CHARACTERISTIC CURVES (For Reference Only)

Fig.1 Average Rectified Output Current Derating Curve

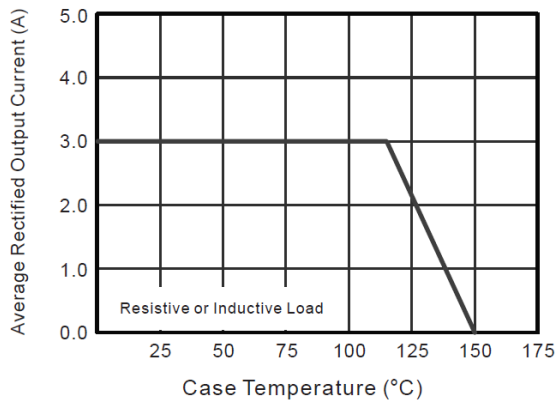


Fig.2 Typical Reverse Characteristics

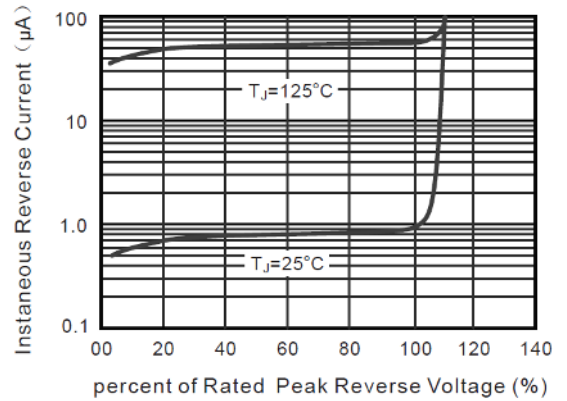


Fig.3 Typical Instantaneous Forward Characteristics

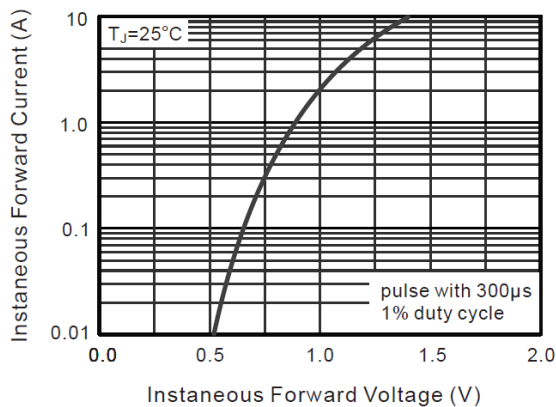


Fig.4 Typical Junction Capacitance

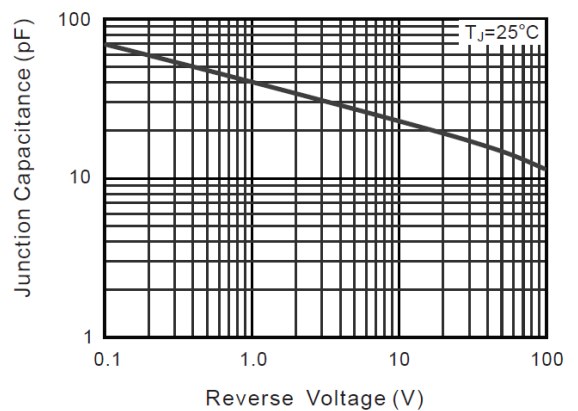
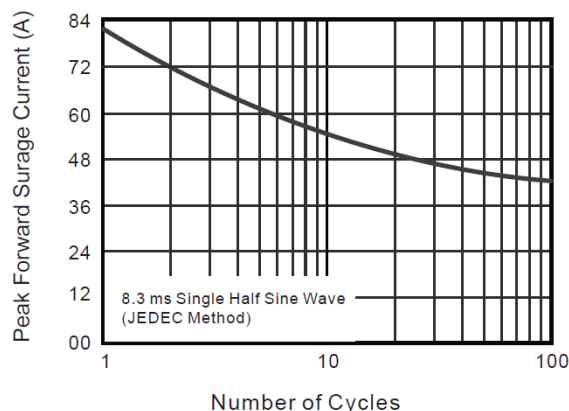


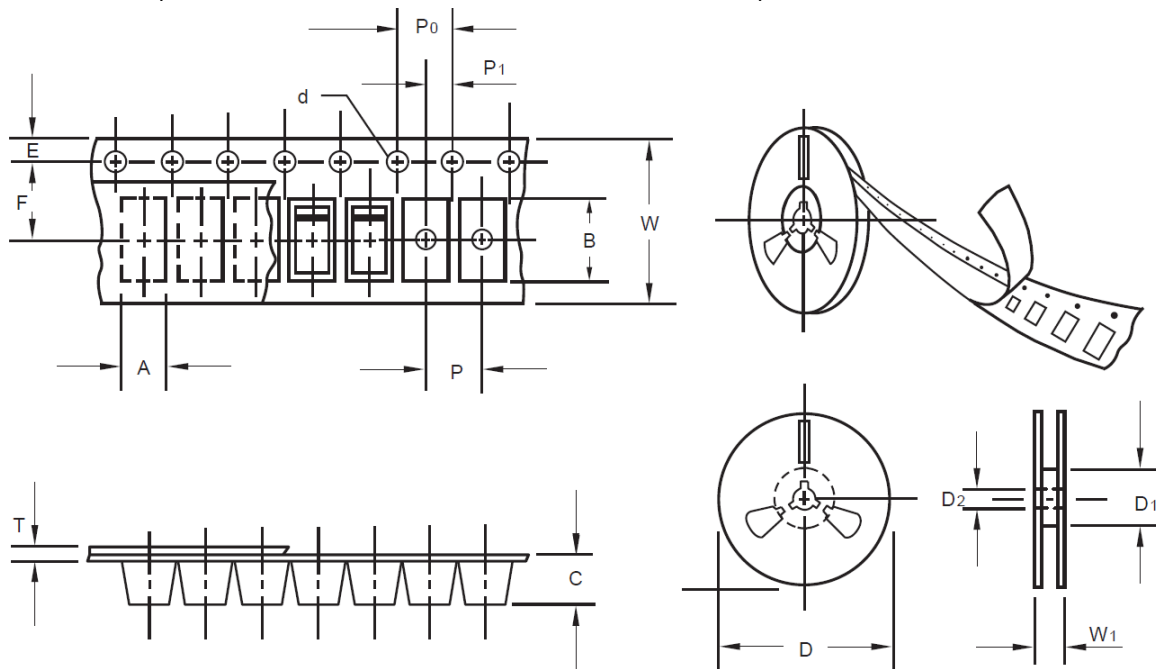
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



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TAPE/REEL (Unit: mm)

All Devices are packed in accordance with EIA standard RS-481-A and specifications.

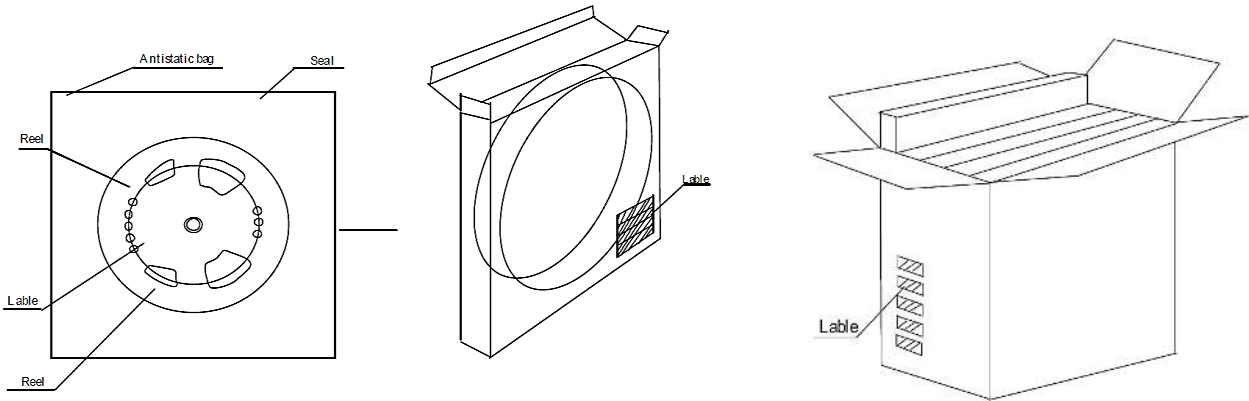


Item	Symbol	Tolerance	UMSB
Carrier width	A	0.1	2.8
Carrier Length	B	0.1	5.33
Carrier Depth	C	0.1	2.36
Sprocket hole	d	0.05	1.50
13"Reel outside diameter	D	2.0	330.00
13"Reel inner diameter	D1	Min.	50.00
7"Reel outside diameter	D	-	-
7"Reel inner diameter	D1	-	-
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.0
Overall tape thickness	T	0.1	0.28
Tape width	W	0.3	12.00
Reel width	W1	1.0	18.0

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PACKAGE

Case Code	Reel Size	MPQ (pcs)	Component Spacing (mm)	Qty. Per Box (pcs)	Inner Box L*W*H (mm)	Reel Size (mm)	Carton size L*W*H (mm)	Qty. Per Carton (pcs)	G. W (kg)
UMSB	13"	3,000	-	6,000	340*340*60	330	380*380*380	48,000	19.6



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